

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chie SHISHIDO	04/22/2013
Maki TANAKA	04/22/2013
Atsushi MIYAMOTO	04/22/2013
Akira HAMAMATSU	04/24/2013
Manabu YANO	05/07/2013
RECEIVING PARTY DATA	
Name:	Hitachi High-Technologies Corporation
Street Address:	24-14, Nishi Shimbashi 1-chome
Internal Address:	Minato-ku
City:	Tokyo
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13880429
CORRESPONDENCE DATA	
Fax Number:	7033126666
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	703-312-6600
Email:	rperez@antonelli.com
Correspondent Name:	ANTONELLI, TERRY, STOUT & KRAUS, LLP
Address Line 1:	1300 NORTH SEVENTEENTH STREET
Address Line 2:	SUITE 1800
Address Line 4:	ARLINGTON, VIRGINIA 22209-3873
ATTORNEY DOCKET NUMBER:	520.53048X00
NAME OF SUBMITTER:	Gregory E. Montone

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PATENT
REEL: 030568 FRAME: 0079

Signature:	/Gregory E. Montone/
Date:	06/07/2013
Total Attachments: 1 source=Assignment#page1.tif	

ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishi Shimbashi 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SHAPE MEASUREMENT METHOD, AND SYSTEM THEREFOR

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	<u>Chie Shishido</u> Chie SHISHIDO	<u>Apr. 22, 2013</u>
2)	<u>Maki Tanaka</u> Maki TANAKA	<u>Apr. 22, 2013</u>
3)	<u>Atsushi Miyamoto</u> Atsushi MIYAMOTO	<u>Apr. 22, 2013</u>
4)	<u>Akira Hamamatsu</u> Akira HAMAMATSU	<u>Apr. 24, 2013</u>
5)	<u>Manabu Yano</u> Manabu YANO	<u>May. 7, 2013</u>
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____